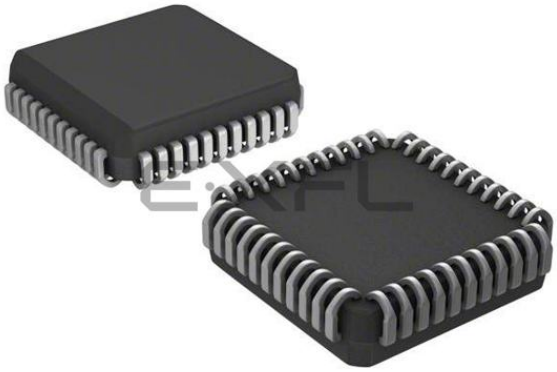


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f442-i-l

TABLE 1-2: PIC18F2X2 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number		Pin Type	Buffer Type	Description
	DIP	SOIC			
					PORTC is a bi-directional I/O port.
RC0/T1OSO/T1CKI	11	11			
RC0			I/O	ST	Digital I/O.
T1OSO			O	—	Timer1 oscillator output.
T1CKI			I	ST	Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2	12	12			
RC1			I/O	ST	Digital I/O.
T1OSI			I	CMOS	Timer1 oscillator input.
CCP2			I/O	ST	Capture2 input, Compare2 output, PWM2 output.
RC2/CCP1	13	13			
RC2			I/O	ST	Digital I/O.
CCP1			I/O	ST	Capture1 input/Compare1 output/PWM1 output.
RC3/SCK/SCL	14	14			
RC3			I/O	ST	Digital I/O.
SCK			I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL			I/O	ST	Synchronous serial clock input/output for I^2C mode
RC4/SDI/SDA	15	15			
RC4			I/O	ST	Digital I/O.
SDI			I	ST	SPI Data In.
SDA			I/O	ST	I^2C Data I/O.
RC5/SDO	16	16			
RC5			I/O	ST	Digital I/O.
SDO			O	—	SPI Data Out.
RC6/TX/CK	17	17			
RC6			I/O	ST	Digital I/O.
TX			O	—	USART Asynchronous Transmit.
CK			I/O	ST	USART Synchronous Clock (see related RX/DT).
RC7/RX/DT	18	18			
RC7			I/O	ST	Digital I/O.
RX			I	ST	USART Asynchronous Receive.
DT			I/O	ST	USART Synchronous Data (see related TX/CK).
VSS	8, 19	8, 19	P	—	Ground reference for logic and I/O pins.
VDD	20	20	P	—	Positive supply for logic and I/O pins.

Legend: TTL = TTL compatible input
CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
I = Input
O = Output
P = Power
OD = Open Drain (no P diode to VDD)

5.2.2 TABLAT - TABLE LATCH REGISTER

The Table Latch (TABLAT) is an 8-bit register mapped into the SFR space. The Table Latch is used to hold 8-bit data during data transfers between program memory and data RAM.

5.2.3 TBLPTR - TABLE POINTER REGISTER

The Table Pointer (TBLPTR) addresses a byte within the program memory. The TBLPTR is comprised of three SFR registers: Table Pointer Upper Byte, Table Pointer High Byte and Table Pointer Low Byte (TBLPTRU:TBLPTRH:TBLPTRL). These three registers join to form a 22-bit wide pointer. The low order 21 bits allow the device to address up to 2 Mbytes of program memory space. The 22nd bit allows access to the Device ID, the User ID and the Configuration bits.

The table pointer, TBLPTR, is used by the `TBLRD` and `TBLWT` instructions. These instructions can update the TBLPTR in one of four ways based on the table operation. These operations are shown in Table 5-1. These operations on the TBLPTR only affect the low order 21 bits.

5.2.4 TABLE POINTER BOUNDARIES

TBLPTR is used in reads, writes, and erases of the FLASH program memory.

When a `TBLRD` is executed, all 22 bits of the Table Pointer determine which byte is read from program memory into TABLAT.

When a `TBLWT` is executed, the three LSbs of the Table Pointer (TBLPTR<2:0>) determine which of the eight program memory holding registers is written to. When the timed write to program memory (long write) begins, the 19 MSbs of the Table Pointer, TBLPTR (TBLPTR<21:3>), will determine which program memory block of 8 bytes is written to. For more detail, see Section 5.5 (“Writing to FLASH Program Memory”).

When an erase of program memory is executed, the 16 MSbs of the Table Pointer (TBLPTR<21:6>) point to the 64-byte block that will be erased. The Least Significant bits (TBLPTR<5:0>) are ignored.

Figure 5-3 describes the relevant boundaries of TBLPTR based on FLASH program memory operations.

TABLE 5-1: TABLE POINTER OPERATIONS WITH `TBLRD` AND `TBLWT` INSTRUCTIONS

Example	Operation on Table Pointer
`TBLRD*` `TBLWT*`	TBLPTR is not modified
`TBLRD*+` `TBLWT*+`	TBLPTR is incremented after the read/write
`TBLRD*-` `TBLWT*-`	TBLPTR is decremented after the read/write
`TBLRD+*` `TBLWT+*`	TBLPTR is incremented before the read/write

FIGURE 5-3: TABLE POINTER BOUNDARIES BASED ON OPERATION

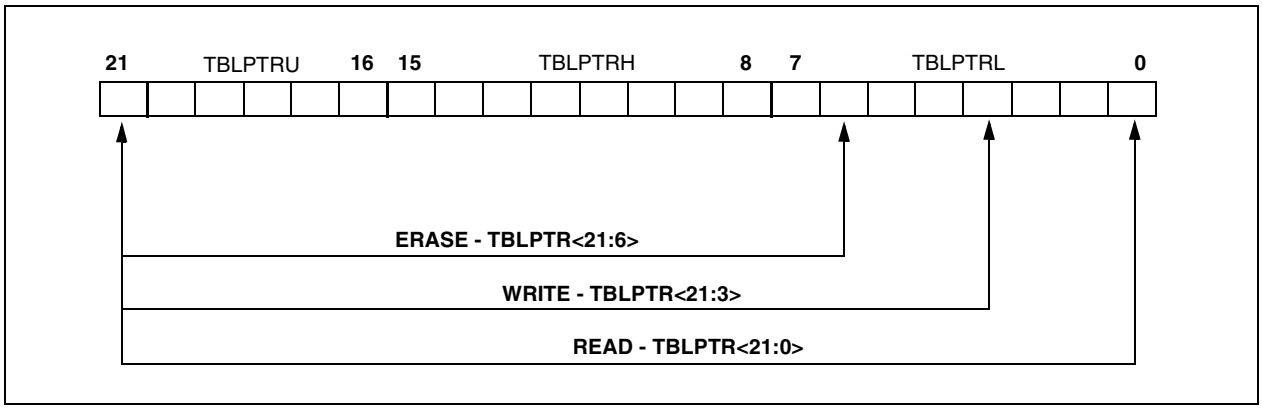
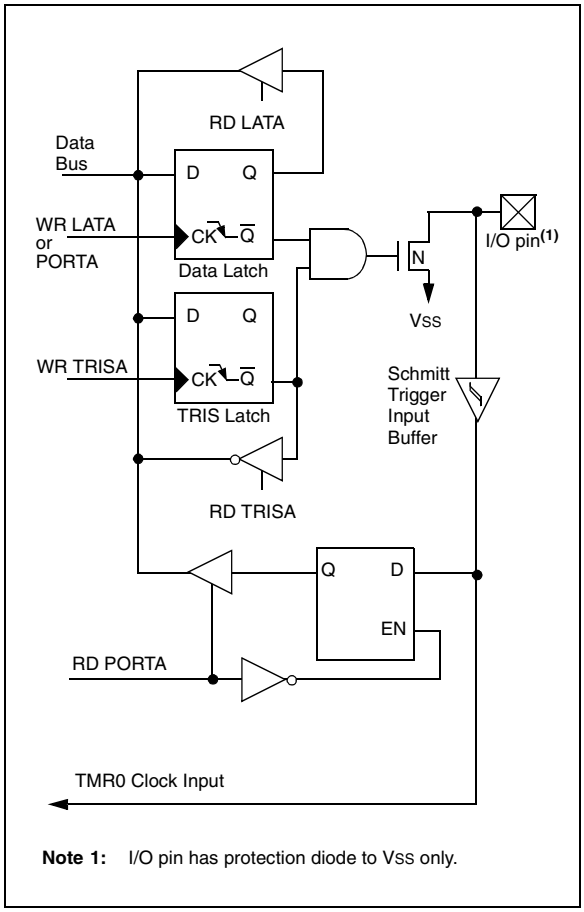
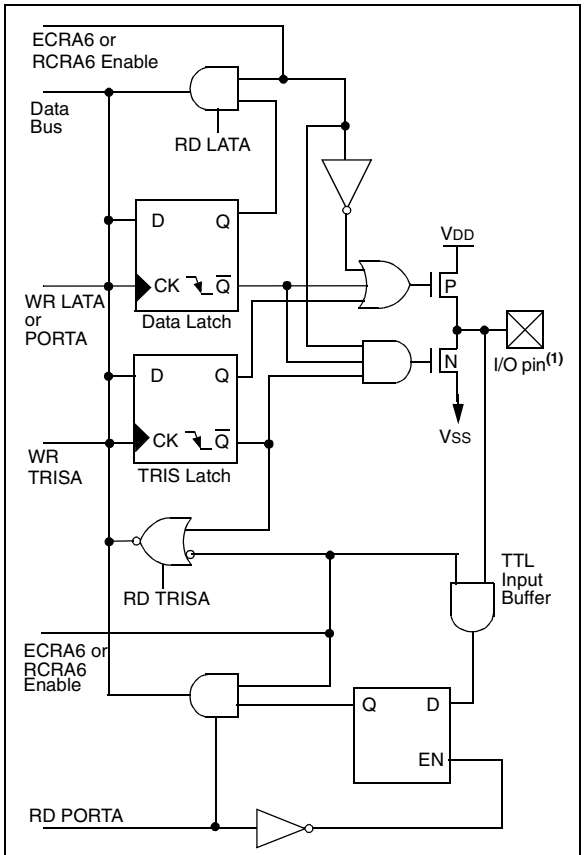


FIGURE 9-2: BLOCK DIAGRAM OF RA4/T0CKI PIN



Note 1: I/O pin has protection diode to VSS only.

FIGURE 9-3: BLOCK DIAGRAM OF RA6 PIN



Note 1: I/O pins have protection diodes to VDD and VSS.

14.4 Compare Mode

In Compare mode, the 16-bit CCPR1 (CCPR2) register value is constantly compared against either the TMR1 register pair value, or the TMR3 register pair value. When a match occurs, the RC2/CCP1 (RC1/CCP2) pin is:

- driven High
- driven Low
- toggle output (High to Low or Low to High)
- remains unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP2M3:CCP2M0). At the same time, interrupt flag bit CCP1IF (CCP2IF) is set.

14.4.1 CCP PIN CONFIGURATION

The user must configure the CCPx pin as an output by clearing the appropriate TRISC bit.

Note:	Clearing the CCP1CON register will force the RC2/CCP1 compare output latch to the default low level. This is not the PORTC I/O data latch.

14.4.2 TIMER1/TIMER3 MODE SELECTION

Timer1 and/or Timer3 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

14.4.3 SOFTWARE INTERRUPT MODE

When generate software interrupt is chosen, the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

14.4.4 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated, which may be used to initiate an action.

The special event trigger output of CCP1 resets the TMR1 register pair. This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

The special trigger output of CCPx resets either the TMR1 or TMR3 register pair. Additionally, the CCP2 Special Event Trigger will start an A/D conversion if the A/D module is enabled.

Note:	The special event trigger from the CCP2 module will not set the Timer1 or Timer3 interrupt flag bits.

FIGURE 14-2: COMPARE MODE OPERATION BLOCK DIAGRAM

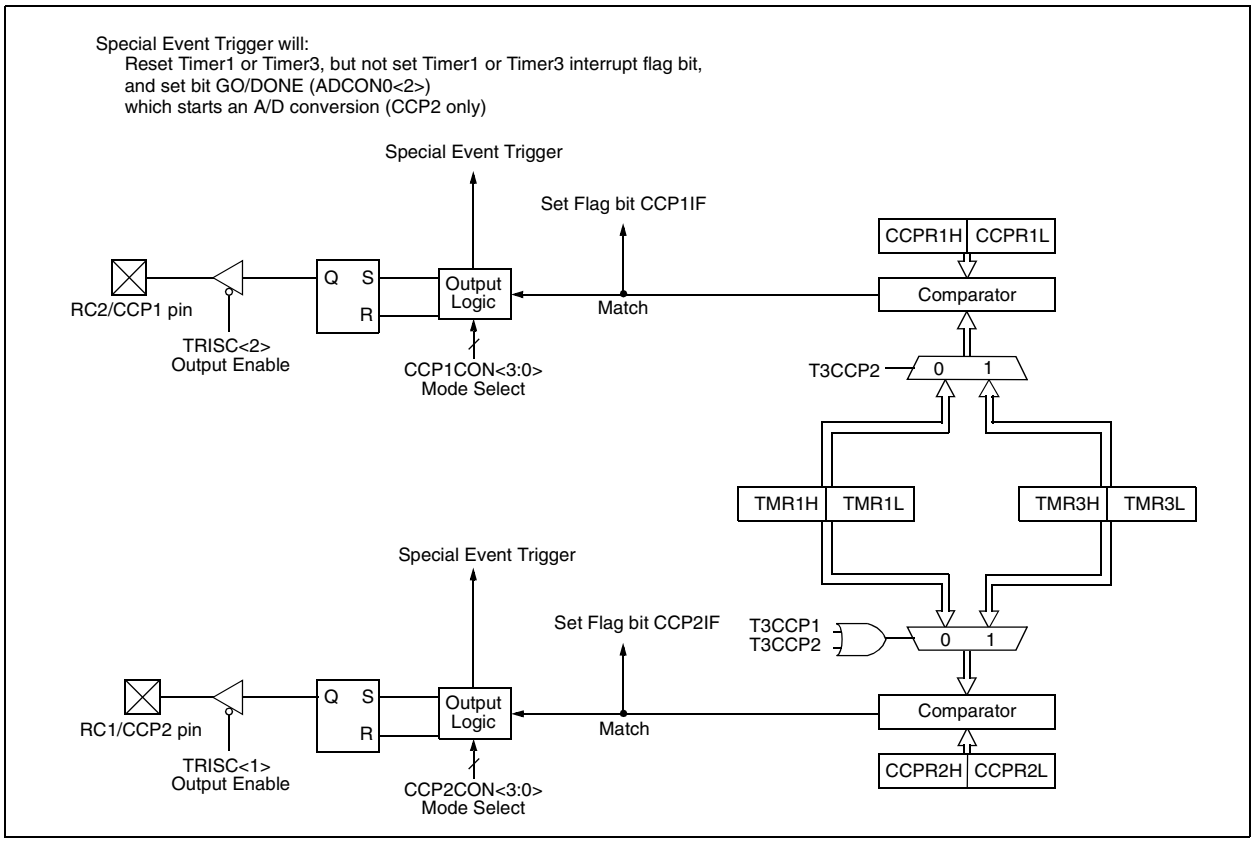


FIGURE 15-9: I²C SLAVE MODE TIMING (TRANSMISSION, 7-BIT ADDRESS)

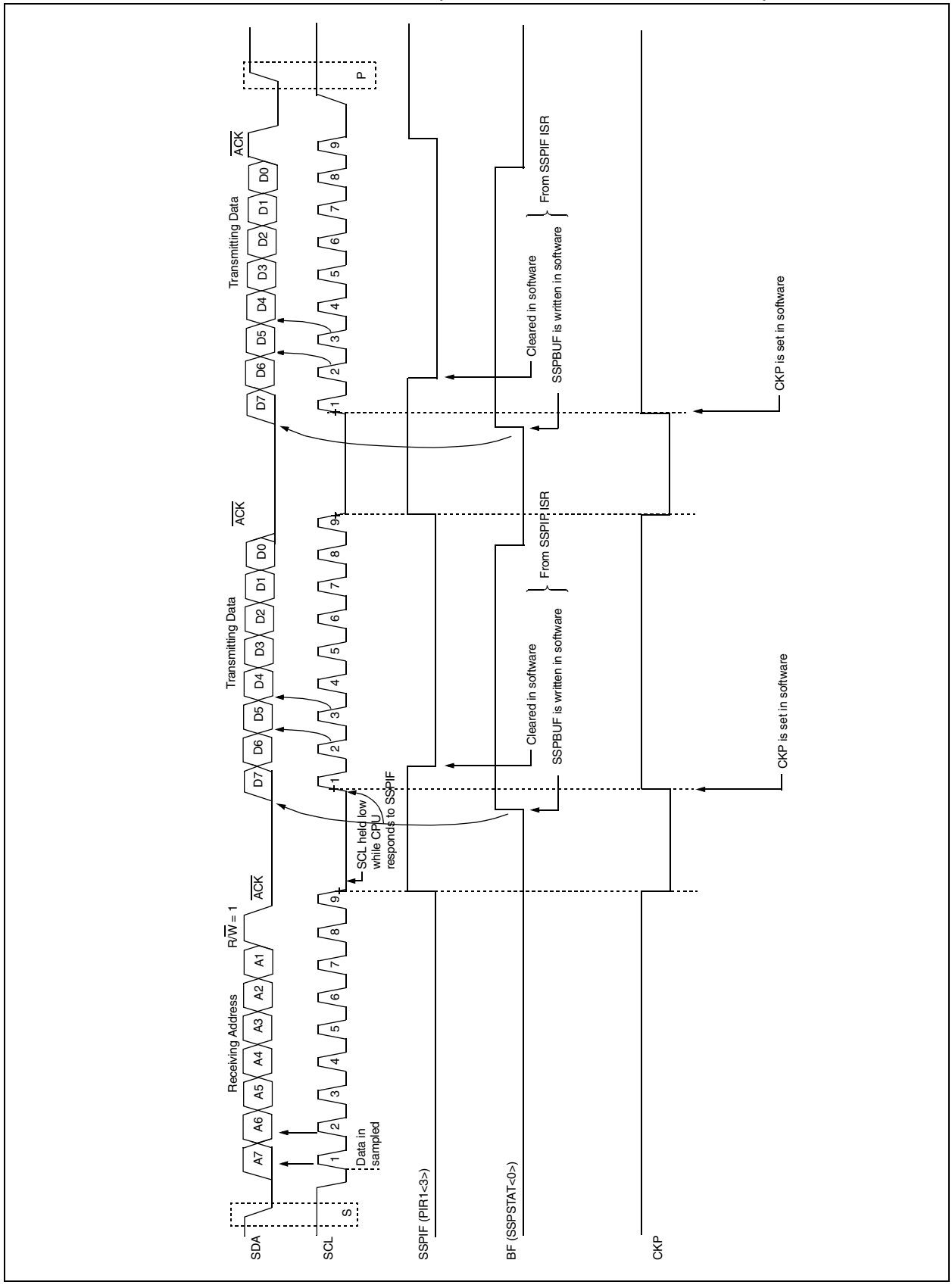
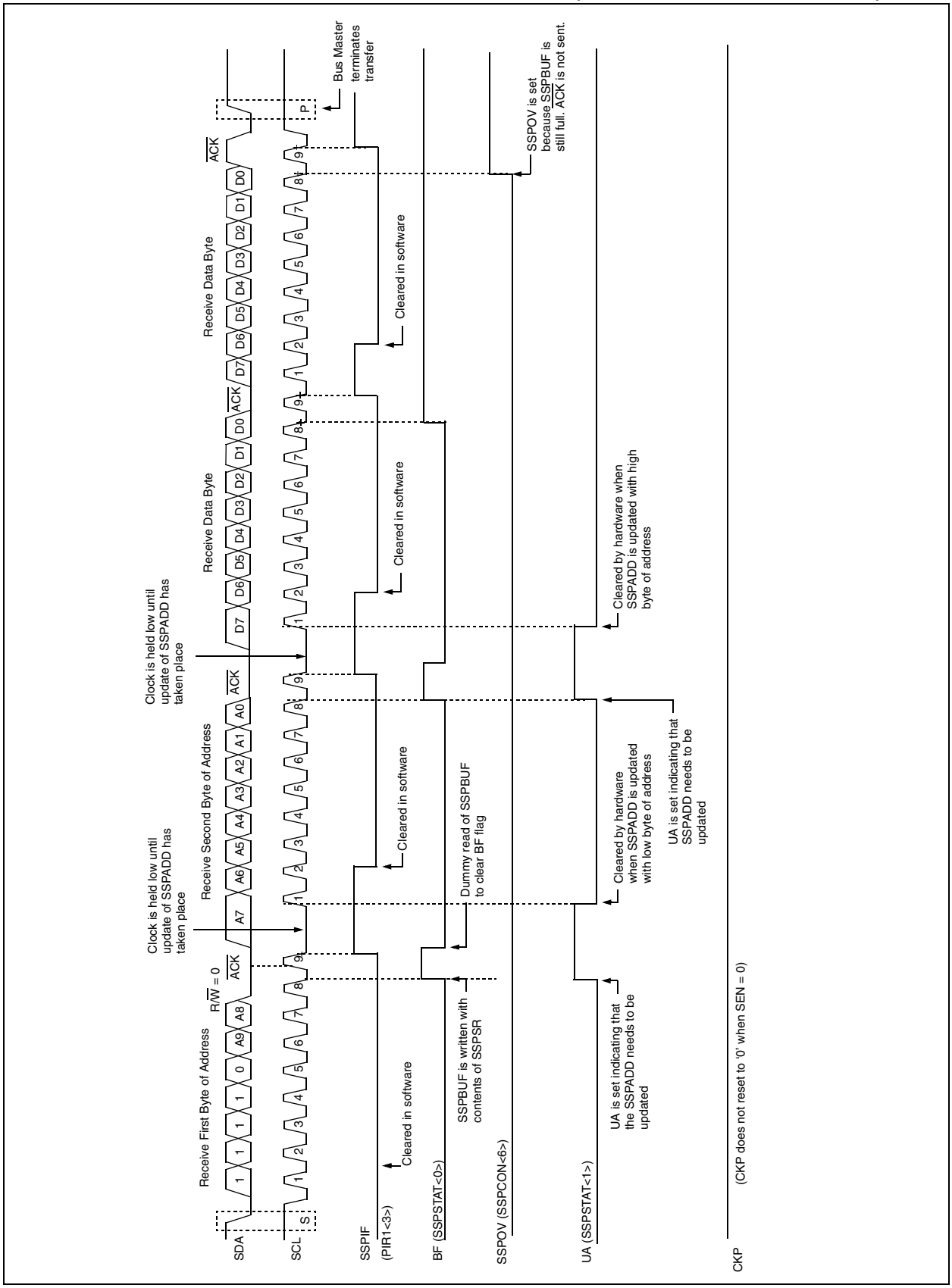


FIGURE 15-10: I²C SLAVE MODE TIMING WITH SEN = 0 (RECEPTION, 10-BIT ADDRESS)



15.4.17.3 Bus Collision During a STOP Condition

Bus collision occurs during a STOP condition if:

a) After the SDA pin has been de-asserted and allowed to float high, SDA is sampled low after the BRG has timed out.

b) After the SCL pin is de-asserted, SCL is sampled low before SDA goes high.

The STOP condition begins with SDA asserted low. When SDA is sampled low, the SCL pin is allowed to float. When the pin is sampled high (clock arbitration), the baud rate generator is loaded with SSPADD<6:0> and counts down to 0. After the BRG times out, SDA is sampled. If SDA is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 15-31). If the SCL pin is sampled low before SDA is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 15-32).

FIGURE 15-31: BUS COLLISION DURING A STOP CONDITION (CASE 1)

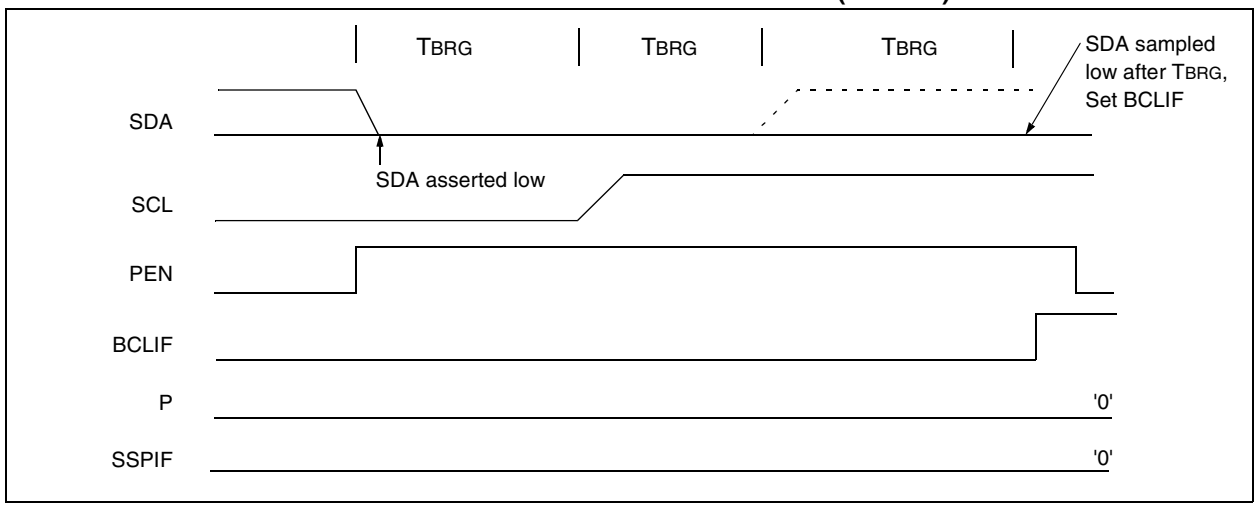
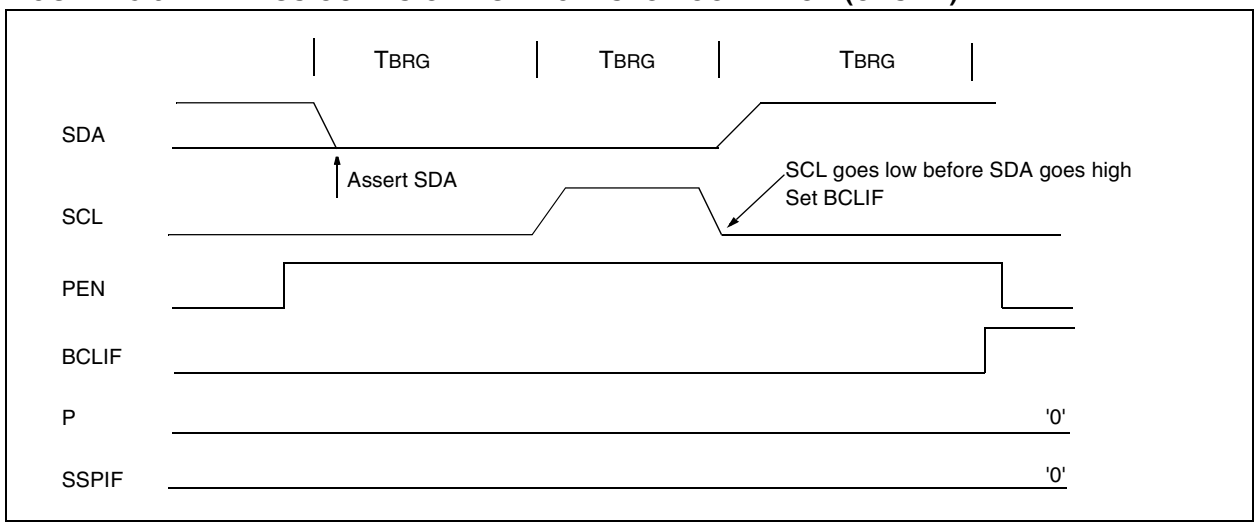


FIGURE 15-32: BUS COLLISION DURING A STOP CONDITION (CASE 2)



The analog reference voltage is software selectable to either the device's positive and negative supply voltage (V_{DD} and V_{SS}), or the voltage level on the RA3/AN3/V_{REF+} pin and RA2/AN2/V_{REF-} pin.

The A/D converter has a unique feature of being able to operate while the device is in SLEEP mode. To operate in SLEEP, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

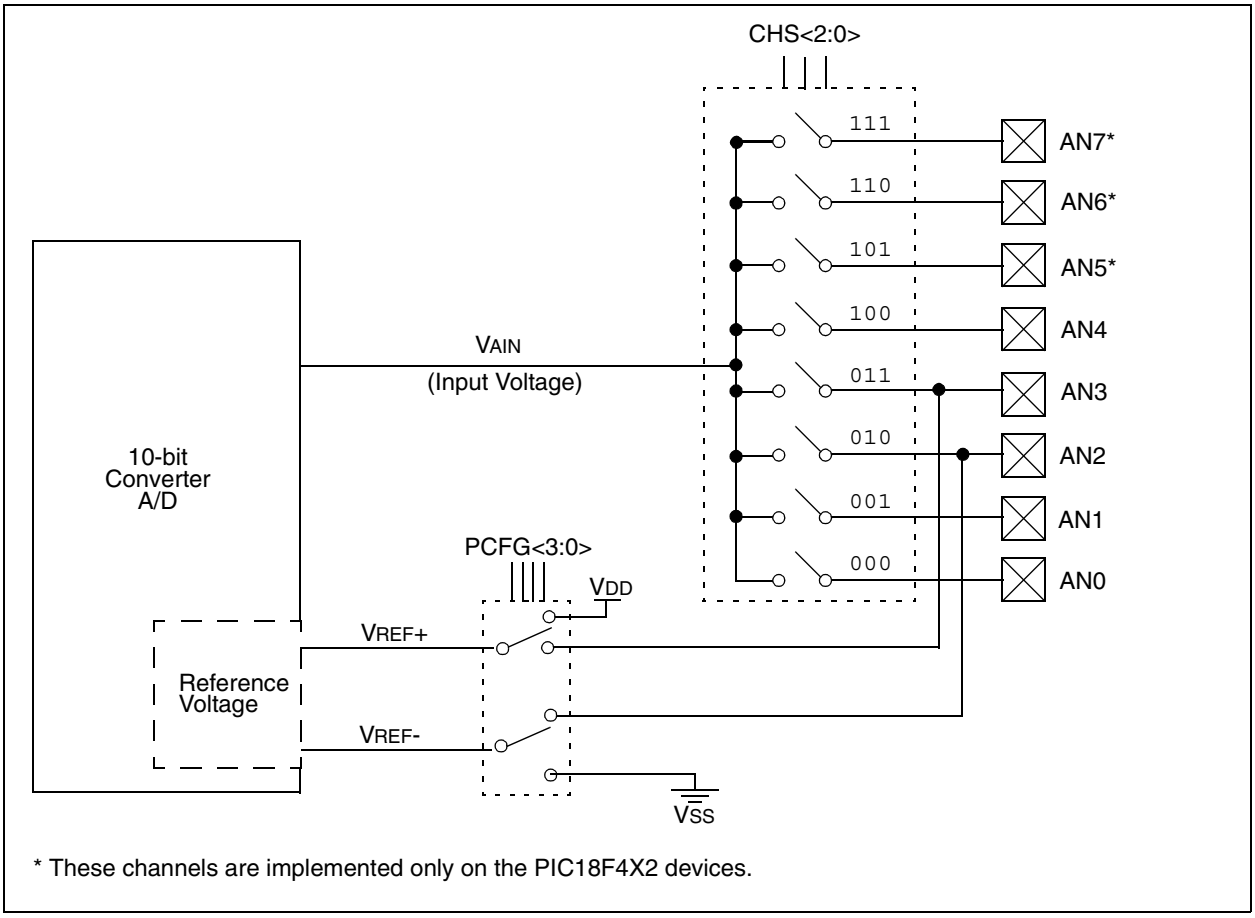
The output of the sample and hold is the input into the converter, which generates the result via successive approximation.

A device RESET forces all registers to their RESET state. This forces the A/D module to be turned off and any conversion is aborted.

Each port pin associated with the A/D converter can be configured as an analog input (RA3 can also be a voltage reference) or as a digital I/O.

The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH/ADRESL registers, the GO/$\overline{\text{DONE}}$ bit (ADCON0<2>) is cleared, and A/D interrupt flag bit, ADIF is set. The block diagram of the A/D module is shown in Figure 17-1.

FIGURE 17-1: A/D BLOCK DIAGRAM



* These channels are implemented only on the PIC18F4X2 devices.

REGISTER 19-4: CONFIGURATION REGISTER 3 HIGH (CONFIG3H: BYTE ADDRESS 300005h)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/P-1
—	—	—	—	—	—	—	CCP2MX
bit 7							bit 0

bit 7-1 **Unimplemented:** Read as '0'

bit 0 **CCP2MX:** CCP2 Mux bit

1 = CCP2 input/output is multiplexed with RC1
0 = CCP2 input/output is multiplexed with RB3

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
- n = Value when device is unprogrammed		u = Unchanged from programmed state

REGISTER 19-5: CONFIGURATION REGISTER 4 LOW (CONFIG4L: BYTE ADDRESS 300006h)

R/P-1	U-0	U-0	U-0	U-0	R/P-1	U-0	R/P-1
$\overline{\text{BKBUG}}$	—	—	—	—	LVP	—	STVREN
bit 7							bit 0

bit 7 $\overline{\textbf{DEBUG}}$**:** Background Debugger Enable bit

1 = Background Debugger disabled. RB6 and RB7 configured as general purpose I/O pins.
0 = Background Debugger enabled. RB6 and RB7 are dedicated to In-Circuit Debug.

bit 6-3 **Unimplemented:** Read as '0'

bit 2 **LVP:** Low Voltage ICSP Enable bit

1 = Low Voltage ICSP enabled
0 = Low Voltage ICSP disabled

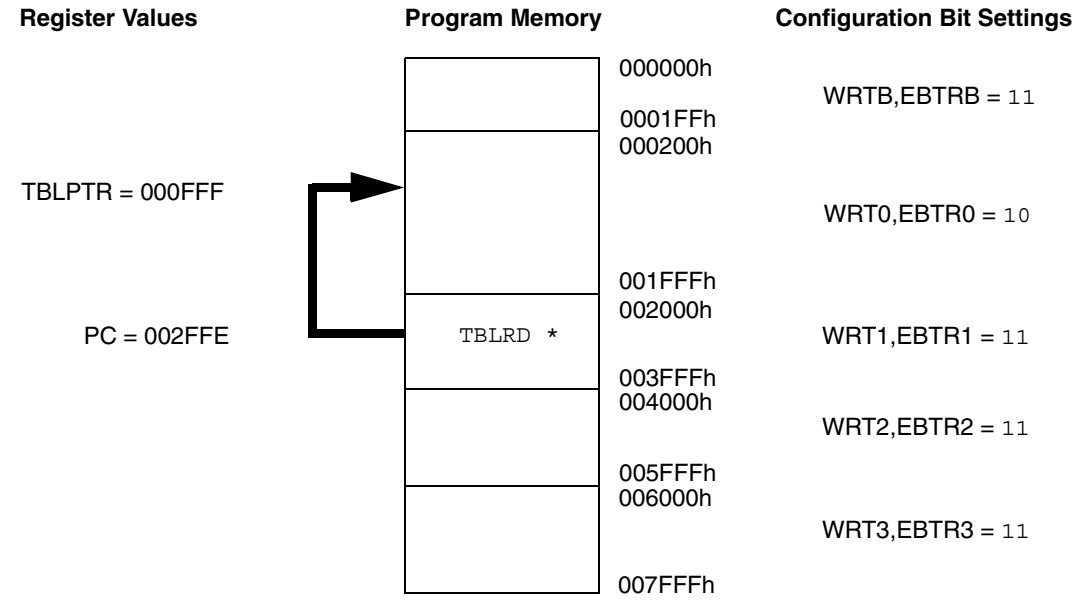
bit 1 **Unimplemented:** Read as '0'

bit 0 **STVREN:** Stack Full/Underflow Reset Enable bit

1 = Stack Full/Underflow will cause RESET
0 = Stack Full/Underflow will not cause RESET

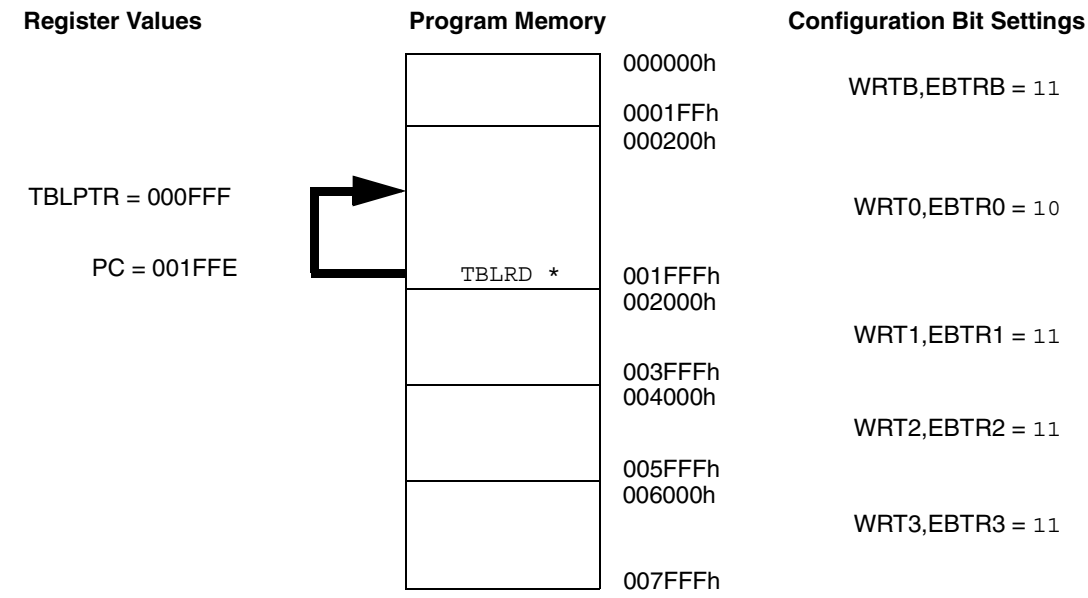
Legend:		
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'
- n = Value when device is unprogrammed		u = Unchanged from programmed state

FIGURE 19-5: EXTERNAL BLOCK TABLE READ (EBTRn) DISALLOWED



Results: All Table Reads from external blocks to Blockn are disabled whenever EBTRn = '0'.
TABLAT register returns a value of "0".

FIGURE 19-6: EXTERNAL BLOCK TABLE READ (EBTRn) ALLOWED



Results: Table Reads permitted within Blockn, even when EBTRBn = '0'.
TABLAT register returns the value of the data at the location TBLPTR.

BTG **Bit Toggle f**

Syntax: [*label*] BTG f,b[,a]

Operands: $0 \le f \le 255$
$0 \le b \le 7$
$a \in [0,1]$

Operation: $(\overline{f<b>}) \rightarrow f<b>$

Status Affected: None

Encoding:

0111	bbba	ffff	ffff

Description: Bit 'b' in data memory location 'f' is inverted. If 'a' is 0, the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: `BTG PORTC, 4, 0`

Before Instruction:
PORTC = 0111 0101 [0x75]
After Instruction:
PORTC = 0110 0101 [0x65]

BOV **Branch if Overflow**

Syntax: [*label*] BOV n

Operands: $-128 \le n \le 127$

Operation: if overflow bit is '1'
$(PC) + 2 + 2n \rightarrow PC$

Status Affected: None

Encoding:

1110	0100	nnnn	nnnn

Description: If the Overflow bit is '1', then the program will branch.
The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC+2+2n. This instruction is then a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:
If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example:
```
HERE    BOV  Jump
```
Before Instruction
PC = address (HERE)
After Instruction
If Overflow = 1;
PC = address (Jump)
If Overflow = 0;
PC = address (HERE+2)

21.0 DEVELOPMENT SUPPORT

The PICmicro® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ® Demonstration Board

21.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows® based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or ‘C’)
- One touch assemble (or compile) and download to PICmicro emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

21.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PICmicro MCU’s.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

21.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI ‘C’ compilers for Microchip’s PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

FIGURE 22-1: PIC18FXX2 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)

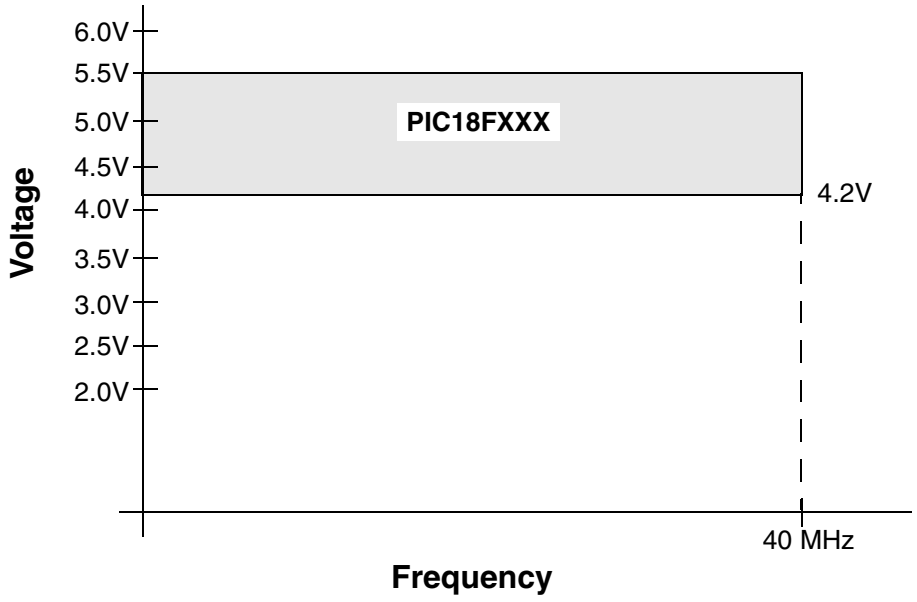
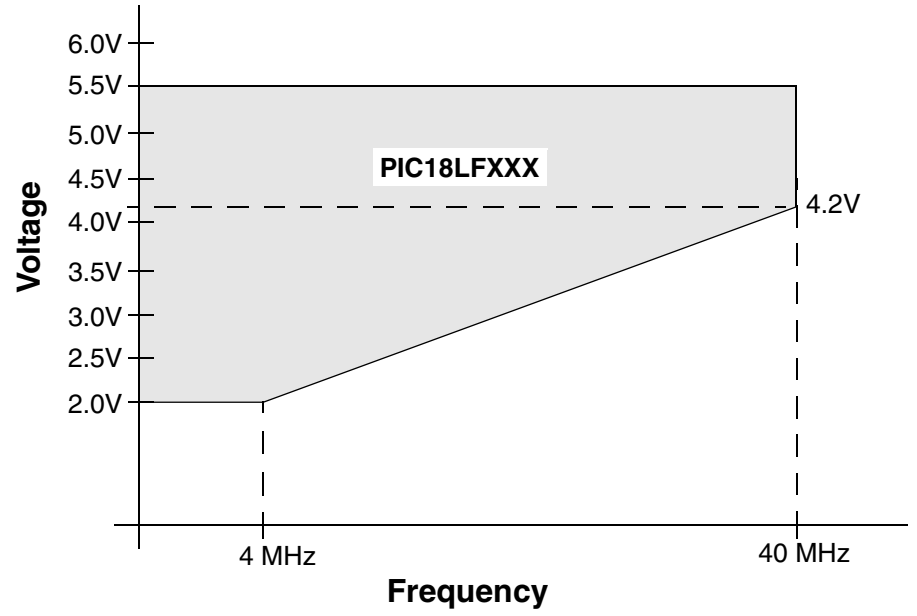


FIGURE 22-2: PIC18LFXX2 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



FMAX = (16.36 MHz/V) (VDDAPPMIN – 2.0V) + 4 MHz

Note: VDDAPPMIN is the minimum voltage of the PICmicro® device in the application.

FIGURE 22-3: LOW VOLTAGE DETECT CHARACTERISTICS

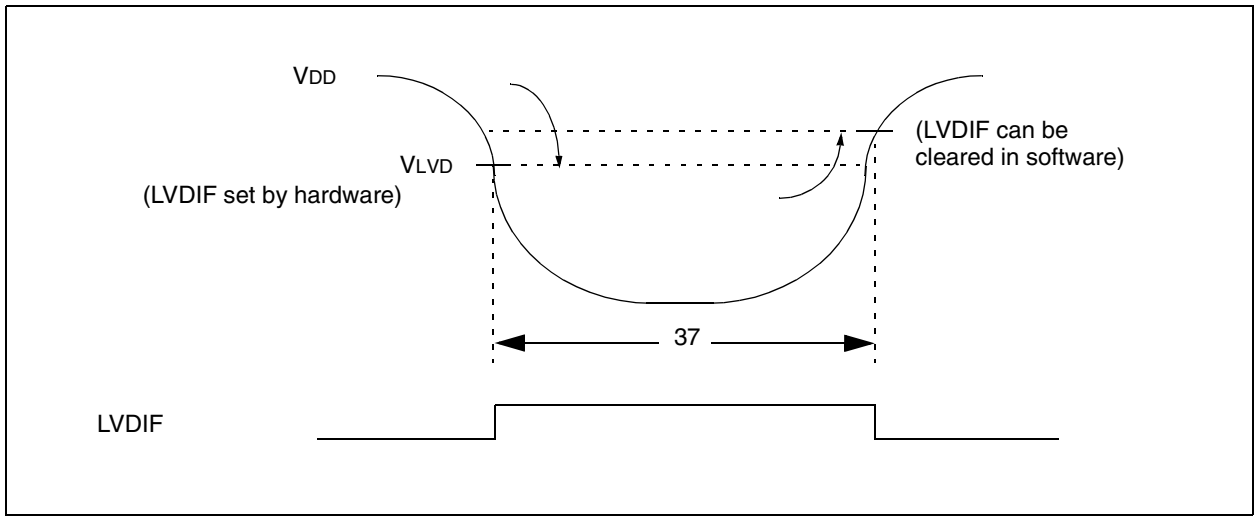


TABLE 22-1: LOW VOLTAGE DETECT CHARACTERISTICS

				Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
D420	VLVD	LVD Voltage on VDD transition high to low	LVV = 0001	1.98	2.06	2.14	V	T ≥ 25°C
			LVV = 0010	2.18	2.27	2.36	V	T ≥ 25°C
			LVV = 0011	2.37	2.47	2.57	V	T ≥ 25°C
			LVV = 0100	2.48	2.58	2.68	V	
			LVV = 0101	2.67	2.78	2.89	V	
			LVV = 0110	2.77	2.89	3.01	V	
			LVV = 0111	2.98	3.1	3.22	V	
			LVV = 1000	3.27	3.41	3.55	V	
			LVV = 1001	3.47	3.61	3.75	V	
			LVV = 1010	3.57	3.72	3.87	V	
			LVV = 1011	3.76	3.92	4.08	V	
			LVV = 1100	3.96	4.13	4.3	V	
			LVV = 1101	4.16	4.33	4.5	V	
			LVV = 1110	4.45	4.64	4.83	V	

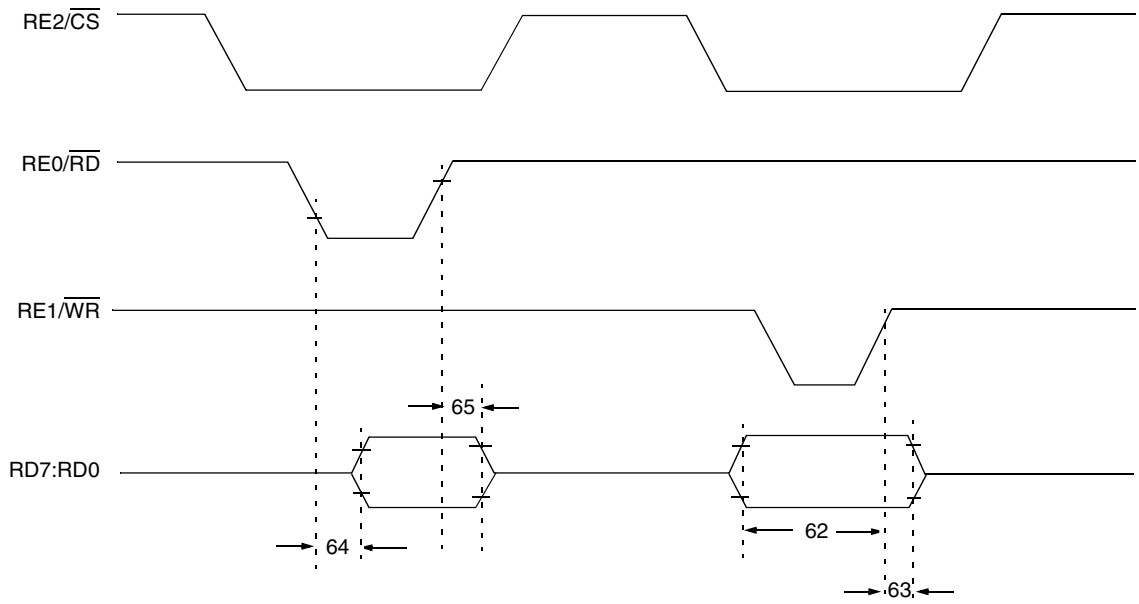
TABLE 22-2: MEMORY PROGRAMMING REQUIREMENTS

DC Characteristics			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Internal Program Memory Programming Specifications					
D110	VPP	Voltage on $\overline{MCLR}$/VPP pin	9.00	—	13.25	V	
D113	IDDP	Supply Current during Programming	—	—	10	mA	
		Data EEPROM Memory					
D120	ED	Cell Endurance	100K	1M	—	E/W	-40°C to +85°C
D121	VDRW	VDD for Read/Write	VMIN	—	5.5	V	Using EECON to read/write VMIN = Minimum operating voltage
D122	TDEW	Erase/Write Cycle Time	—	4	—	ms	
D123	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated
D124	TREF	Number of Total Erase/Write Cycles before Refresh(1)	1M	10M	—	E/W	-40°C to +85°C
		Program FLASH Memory					
D130	EP	Cell Endurance	10K	100K	—	E/W	-40°C to +85°C
D131	VPR	VDD for Read	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D132	VIE	VDD for Block Erase	4.5	—	5.5	V	Using ICSP port
D132A	VIW	VDD for Externally Timed Erase or Write	4.5	—	5.5	V	Using ICSP port
D132B	VPEW	VDD for Self-timed Write	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D133	TIE	ICSP Block Erase Cycle Time	—	4	—	ms	VDD ≥ 4.5V
D133A	TIW	ICSP Erase or Write Cycle Time (externally timed)	1	—	—	ms	VDD ≥ 4.5V
D133A	TIW	Self-timed Write Cycle Time	—	2	—	ms	
D134	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Refer to Section 6.8 for a more detailed discussion on data EEPROM endurance.

FIGURE 22-11: PARALLEL SLAVE PORT TIMING (PIC18F4X2)

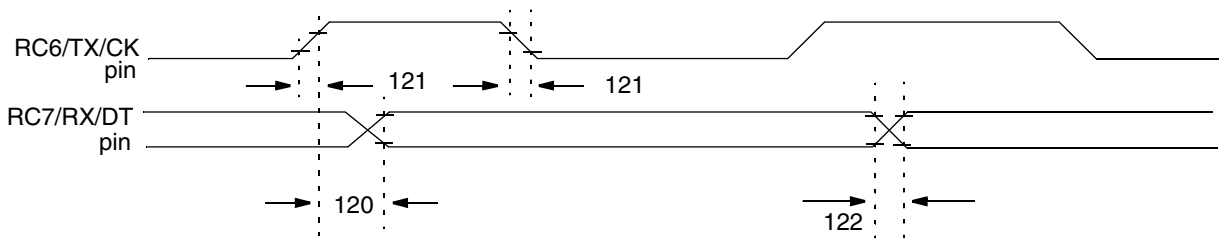


Note: Refer to Figure 22-4 for load conditions.

TABLE 22-10: PARALLEL SLAVE PORT REQUIREMENTS (PIC18F4X2)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
62	TdtV2wrH	Data in valid before $\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ (setup time)		20 25	— —	ns ns	 Extended Temp. Range
63	TwrH2dtI	$\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ to data–in invalid (hold time)	PIC18**F**XXX	20	—	ns	
			PIC18**LF**XXX	35	—	ns	V_{DD} = 2V
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid		— —	80 90	ns ns	 Extended Temp. Range
65	TrdH2dtI	$\overline{RD}\uparrow$ or $\overline{CS}\downarrow$ to data–out invalid		10	30	ns	
66	TibfINH	Inhibit of the IBF flag bit being cleared from $\overline{WR}\uparrow$ or $\overline{CS}\uparrow$		—	3 TCY		

FIGURE 22-20: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

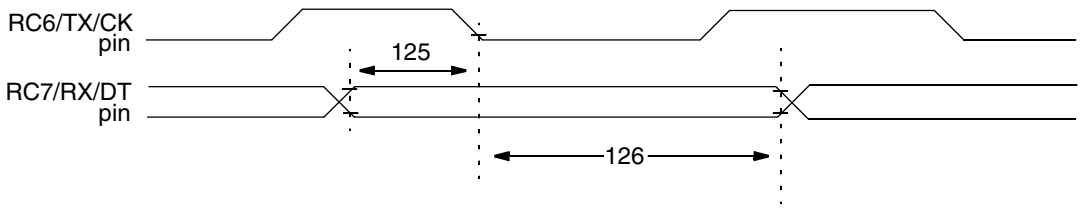


Note: Refer to Figure 22-4 for load conditions.

TABLE 22-19: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	PIC18**F**XXX	—	50	ns	
			PIC18**LF**XXX	—	150	ns	VDD = 2V
121	Tckr	Clock out rise time and fall time (Master mode)	PIC18**F**XXX	—	25	ns	
			PIC18**LF**XXX	—	60	ns	VDD = 2V
122	Tdtr	Data out rise time and fall time	PIC18**F**XXX	—	25	ns	
			PIC18**LF**XXX	—	60	ns	VDD = 2V

FIGURE 22-21: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 22-4 for load conditions.

TABLE 22-20: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
125	TdtV2ckl	SYNC RCV (MASTER & SLAVE) Data hold before CK ↓ (DT hold time)		10	—	ns	
126	TckL2dtl	Data hold after CK ↓ (DT hold time)	PIC18**F**XXX	15	—	ns	
			PIC18**LF**XXX	20	—	ns	VDD = 2V

FIGURE 23-5: TYPICAL IDD vs. FOSC OVER VDD (XT MODE)

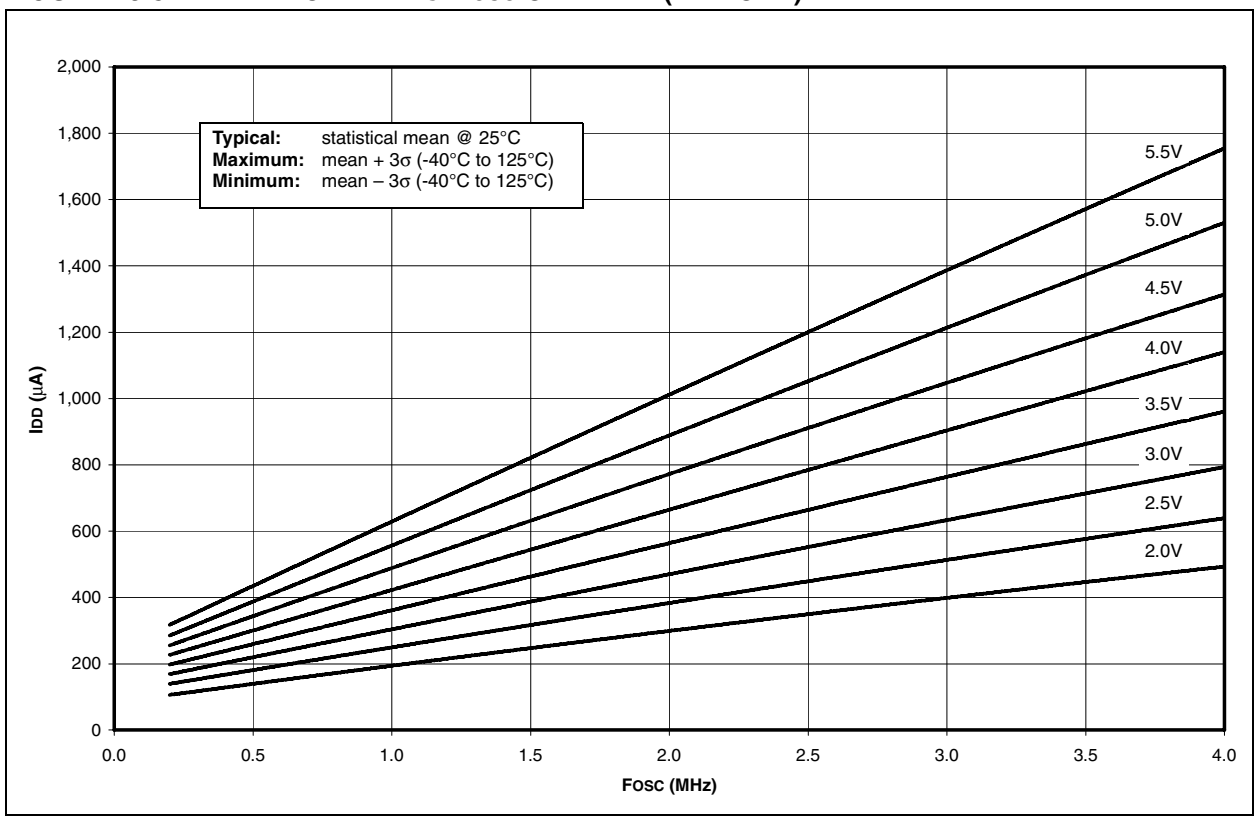
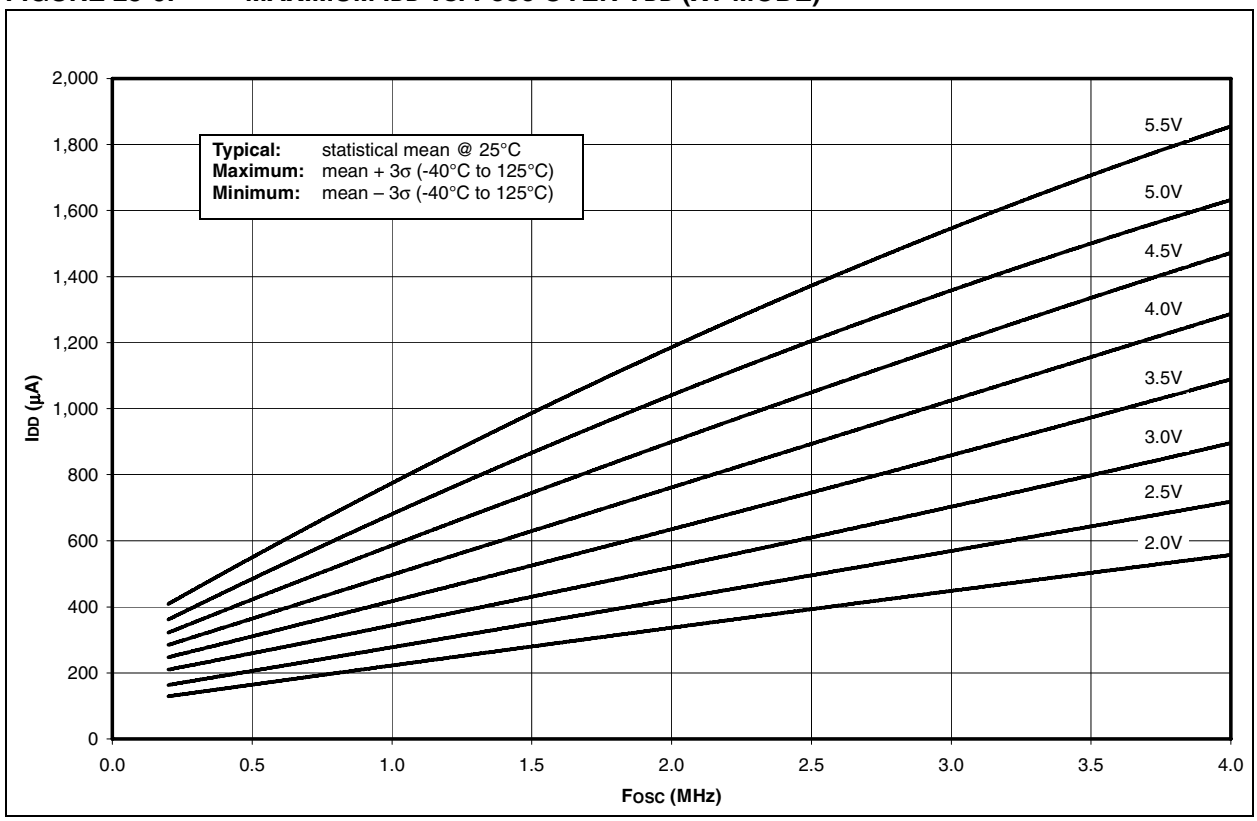


FIGURE 23-6: MAXIMUM IDD vs. FOSC OVER VDD (XT MODE)



P

U